Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED
THIS PAGE INTENTIONALLY LEFT BLANK
**Facilities, Manufacturing & Test**
- Class 100 Environment for S-Level Products
- Automatic Hybrid Assembly Equipment: Die Inspect/Pick, Die/Substrate Attach & Wire Bond
- IR Reflow Equipment for PCB Based Assemblies
- Automated Digital Product Test to 40 Gbps
- Automated RF, Microwave & Millimeterwave Product Test to 110 GHz

**High Reliability Screening & Tests**
- Wafer Lot Acceptance Test (WLAT) Bond Pull & Die Shear SEM Inspection Metal & Dielectric Thickness Meas.
- Temperature Cycle
- Constant Acceleration
- High Temp Burn-In
- Visual Inspection
- Vibration
- Fine & Gross Hermeticity
- Radiographic Inspection
- Particle Impact Noise Detection
- Residual Gas Analysis
- ESD Characterization
- Serialized Test Data
- Qualification Report

**Hittite Delivers Qualified Solutions to Meet Your Specific Requirements!**

**Contact Us:** mil@hittite.com
Hittite Provides Proven Technical Solutions for Military Applications!

- Vertical Integration with In-House MMIC & Module Design and Manufacturing
- Rapid Prototyping Capability Reduces Technical & Schedule Risks
- Custom IC Development Enables Advanced Performance with Miniature Size
- IC Manufacturing Infrastructure Provides Benefits in Controlling Performance, Quality, Schedule, Obsolescence, Packaging & Design Optimization
- Demonstrated Track Record of Industry Leadership and Key Supplier to the World’s Most Trusted Defense System Integrators

World-Class IC, Module, and Subsystem Design and Manufacturing Solutions!

Contact Us: mil@hittite.com
**Space Manufacturing**

Space Qualified Processes, People & Facilities!

Analog, Digital & Mixed-Signal ICs, Modules, Subsystems & Instrumentation

---

**Facilities, Manufacturing & Test**

- Class 100 Environment for S-Level Products
- Automatic Hybrid Assembly Equipment: Die Inspect/Pick, Die/Substrate Attach & Wire Bond
- IR Reflow Equipment for PCB Based Assemblies
- Automated Digital Product Test to 40 Gbps
- Automated RF, Microwave & Millimeterwave Product Test to 110 GHz

---

**Class S Screening & Qualification**

- VI to Methods 2010A & 2017K
- Temperature Cycle
- High Temperature Burn-In & Life Test
- Wafer Lot Acceptance Test
  - Bond Pull & Die Shear
  - SEM Inspection
  - Metal & Dielectric Thickness Meas.
- Serialized Test Data
- Qualification Report

---

**Hittite Delivers Qualified Solutions to Meet Your Specific Requirements!**

**Contact Us:** space@hittite.com

---

Visit Us: www.hittite.com
Receive the latest product releases - click on “My Subscription”
Space Products

Space Qualified Components, Modules & Subsystems!

Analog, Digital & Mixed-Signal ICs, Modules, Subsystems & Instrumentation

Hittite Provides Proven Technical Solutions for Space Applications!

- Space Upscreening to Customer Specifications & Delivered over 45,000 S-Level Components
- Qualified By Major Spacecraft OEMs
- Space Level Products, Component & Module Qualification
- Offers MIL-PRF-38534-K & MIL-PRF-38535-S Class Screening on Die, Hermetic, Packaged Die & Hybrid Assemblies
- Space Grade Components Currently Operational on Dozens of Commercial, Scientific & Military Spacecraft

Your Source for State-of-the-Art Proven Performance!

Contact Us: space@hittite.com

Visit Us: www.hittite.com
Receive the latest product releases - click on "My Subscription"